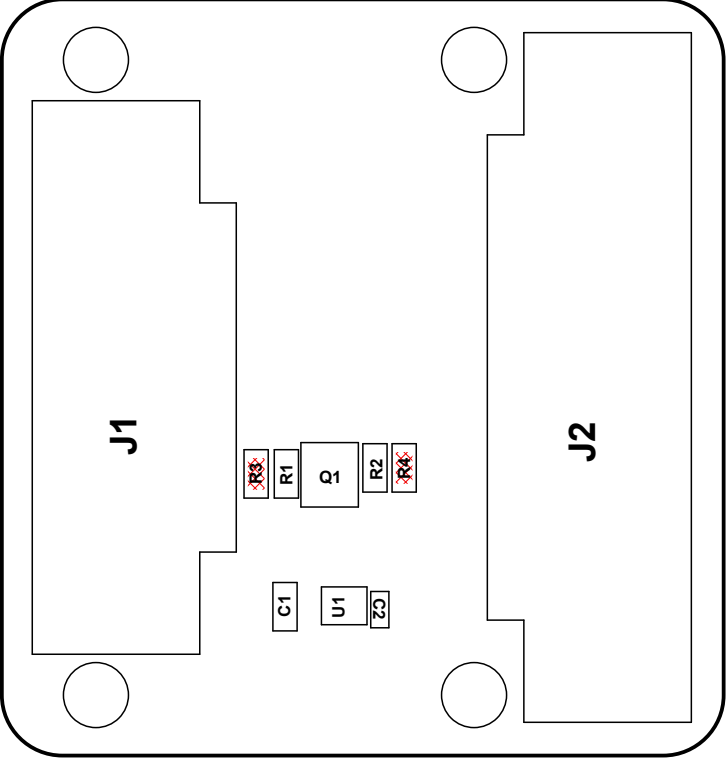



ASSEMBLY NOTES:

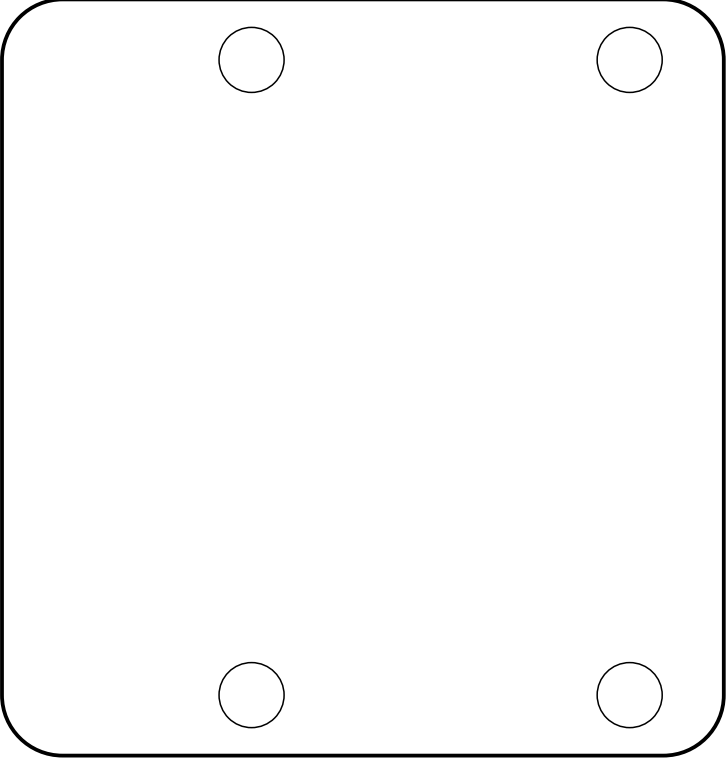
- Assembly shall conform to IPC-A-610 Class 2.
- Assembly shall conform with RoHS Directive 2011/65/EU.
- Components shall be placed according to the associated CPL and BOM documents.
- Lead-free SAC305 solder shall be used.
- Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.
- BGA components shall be 100% checked with x-ray for solder bridges after reflow.
- Finished assemblies shall be removed from panel prior to delivery.


View from Top side (Scale 4:1)



Title: SL6996	
Number: D2088000 Revision: =rev	
Date: 29/05/2023 Sheet: 1 of 2	PROPRIETARY AND CONFIDENTIAL
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[Variant: Production] View from Bottom side (Scale 4:1)



Title: SL6996	
Number: D2088000 Revision: =rev	
Date: 29/05/2023 Sheet: 2 of 2	PROPRIETARY AND CONFIDENTIAL
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RoHS

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